



SUSS MICROTEC INVESTOR PRESENTATION

May/June 2013

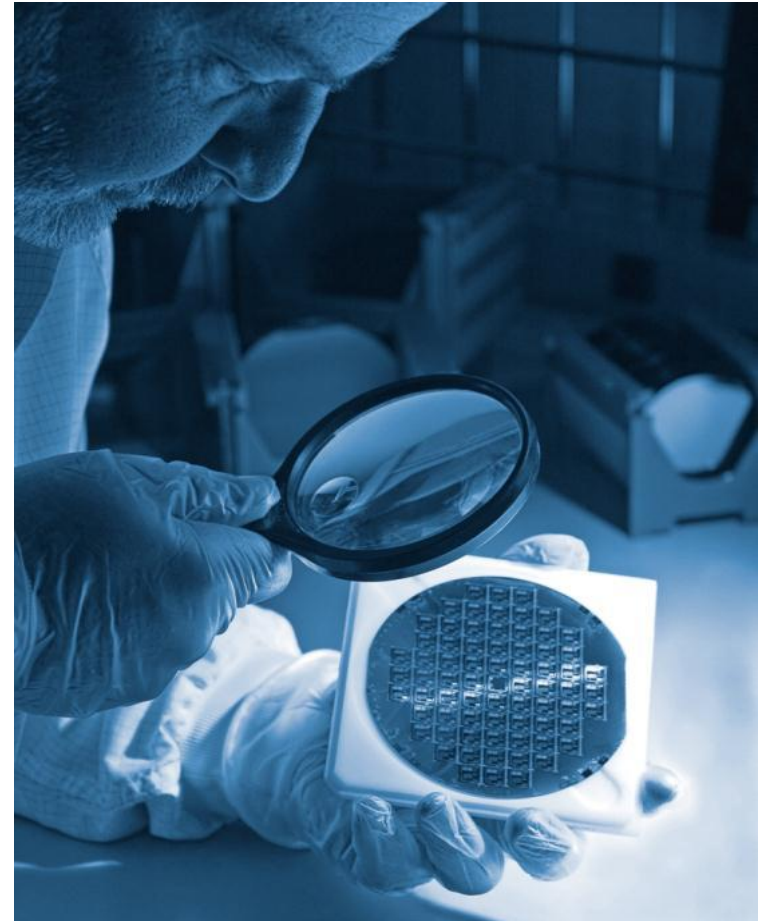
This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

- I. SUSS MicroTec at a Glance**
- II. Products and Markets
- III. Growth Opportunities
- IV. Enhancement of Lithography Portfolio
- V. Financials
- VI. Outlook
- VII. Backup

- + SUSS MicroTec: A global leader in semiconductor equipment
- + Our equipment and process solutions create the micro structures that build and connect micro electronic devices
- + We are focused on high growth market segments: Semiconductors, MEMS, LEDs

+ Key Data:

- Stock Exchange Symbol: SMHN
- TecDAX
- Share price*: 8.69 €
- Market Cap*: 166 € million
- Net Cash, March 31, 2012: 25.1 € million



* April 30, 2013

EXTENSIVE PRODUCT PORTFOLIO



Photomask Equipment



Coater/Developer



Wafer Bonders



**Alignment
Verification Systems**



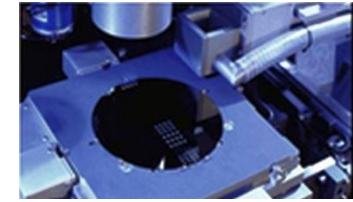
Mask Aligners



Imprinting Systems

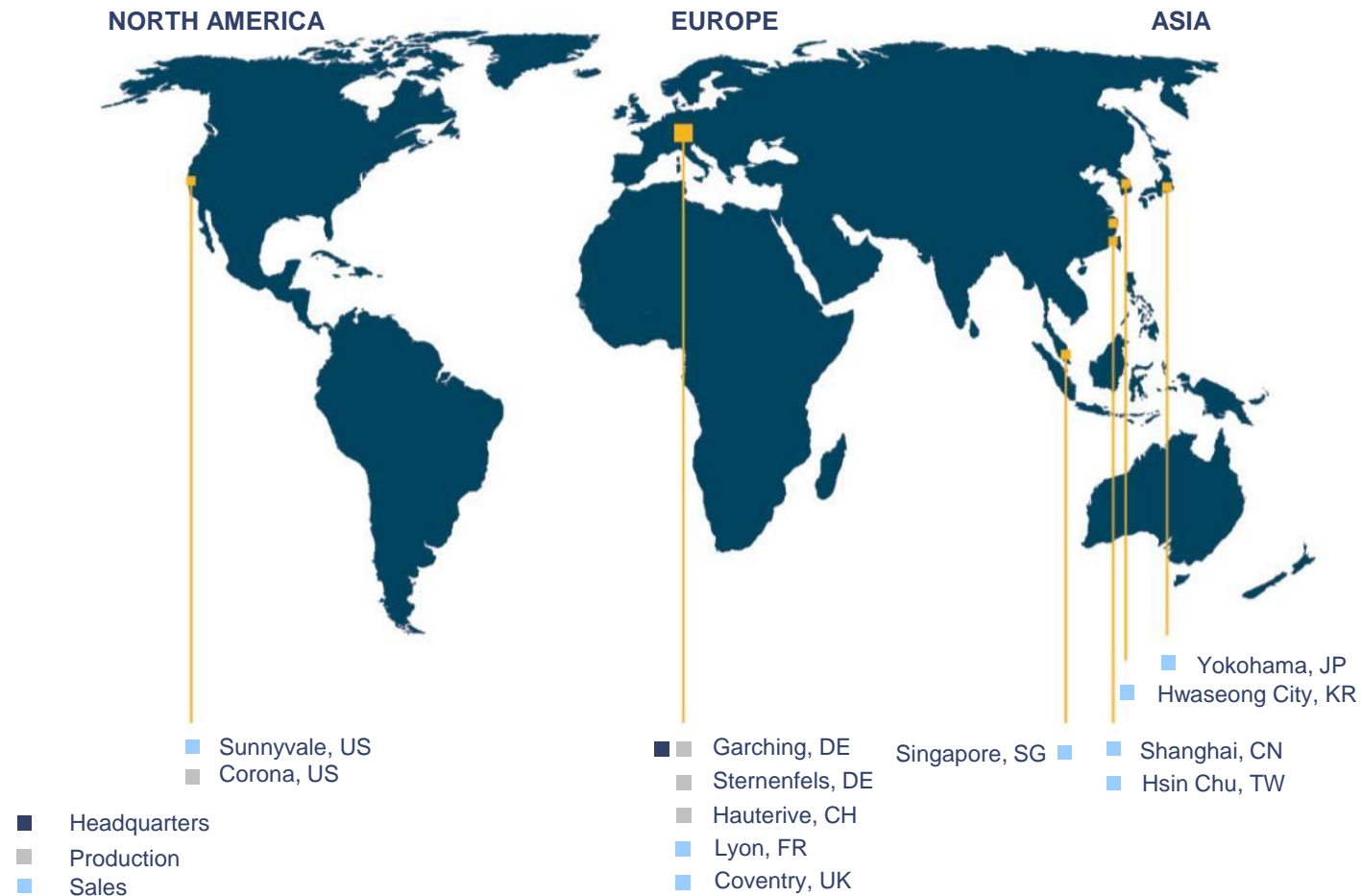


**UV-Projection
Stepper / Scanner**



**Excimer Laser
Systems**

SUSS MICROTEC – A GLOBAL PLAYER



Germany



Garching

- + SUSS MicroTec HQ
- + Development/production:
 - **Mask Aligner**
 - **Bond Aligner**
- + Core competencies:
 - **Exposure**
(proximity exposure)
 - **Alignment**



Sternenfels

- + Development/production :
 - **Bonder**
 - **Coater and Developer**
 - **Photomask Equipment**
- + Core competencies:
 - **Wet processing**
 - **Wafer bonding**

USA

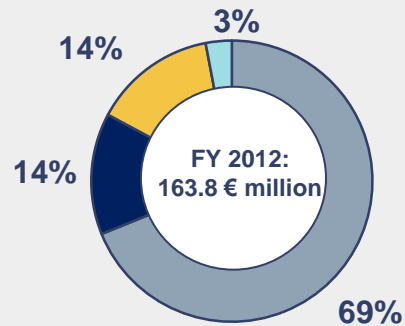


Corona

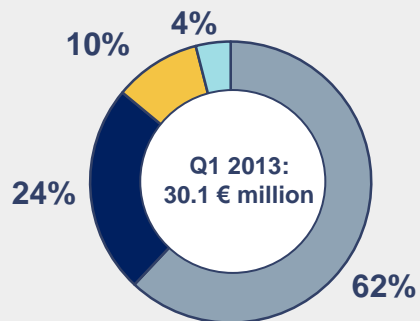
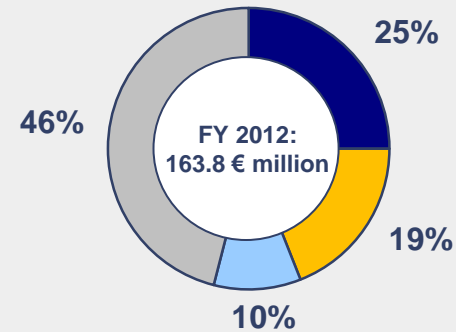
- + Development/production:
 - **Stepper/Scanner**
 - **Laser Processing**
- + Core competencies:
 - **Exposure**
(UV projection lithography)
 - **Laser Ablation**

SALES BY SEGMENT AND REGION 2012 AND Q1 2013

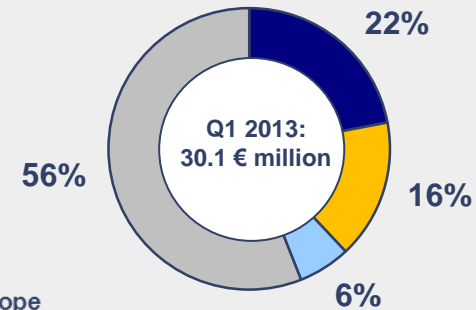
Sales by Segment



Sales by Region



■ Lithography
■ Photomask Equipment
■ Substrate Bonder
■ Others



■ Europe
■ North America
■ Japan
■ Rest of Asia

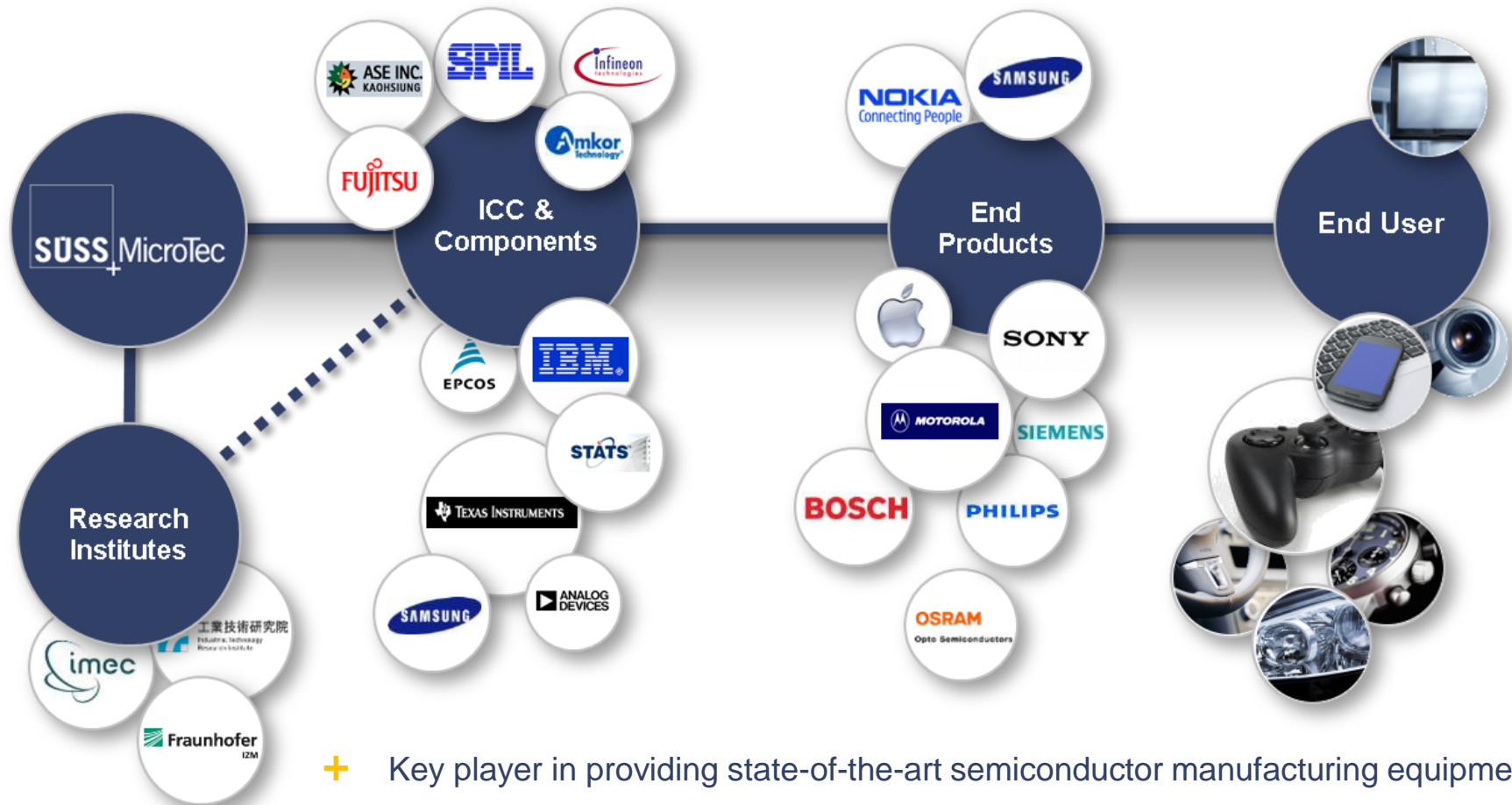
- + Re-alignment of Permanent Bonding with focus on MEMS and LED market to address the unsatisfying earnings level
- + Non-cash adjustment of € 6.8 million in Q2 2013 with write-offs on capitalized development costs (from 2008 and before), demonstration tools and inventories
- + Growth of Substrate Bonder division will mainly be driven by Temporary Bonding, which has been successfully established in the market
- + Sales contribution of Permanent Bonding product line will for the time being remain at the level of the previous year

The Substrate Bonder division is well positioned to benefit from the expected growth in the target markets

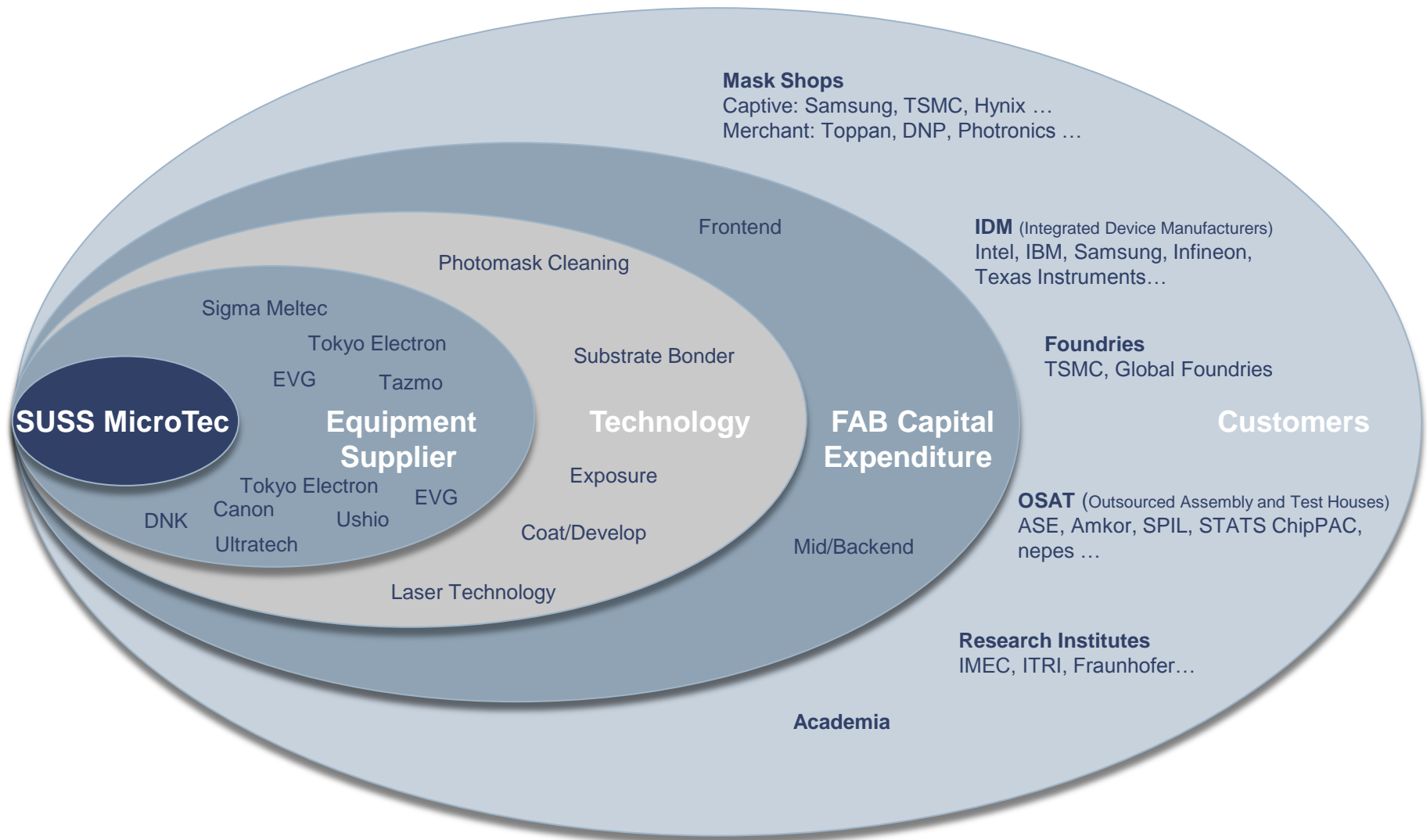
3D IC, MEMS and LED

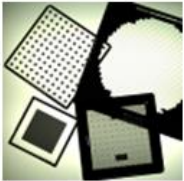
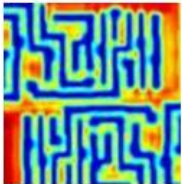
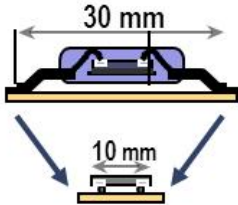
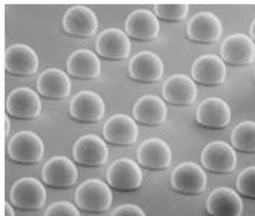
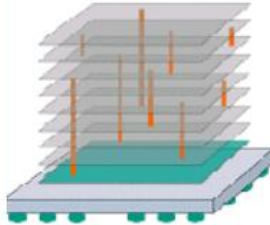
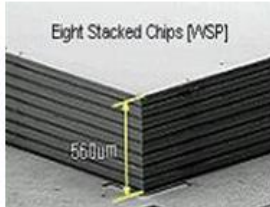

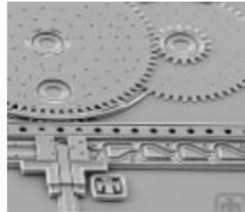
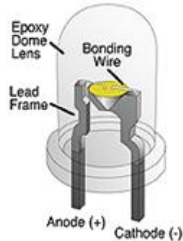

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SUSS MICROTEC IN THE VALUE CHAIN



- + Key player in providing state-of-the-art semiconductor manufacturing equipment
- + Development of highly innovative process solutions with industry and R&D partners
- + Components for electronic devices like cell phones, PCs and tablet computers are produced on SUSS MicroTec's equipment

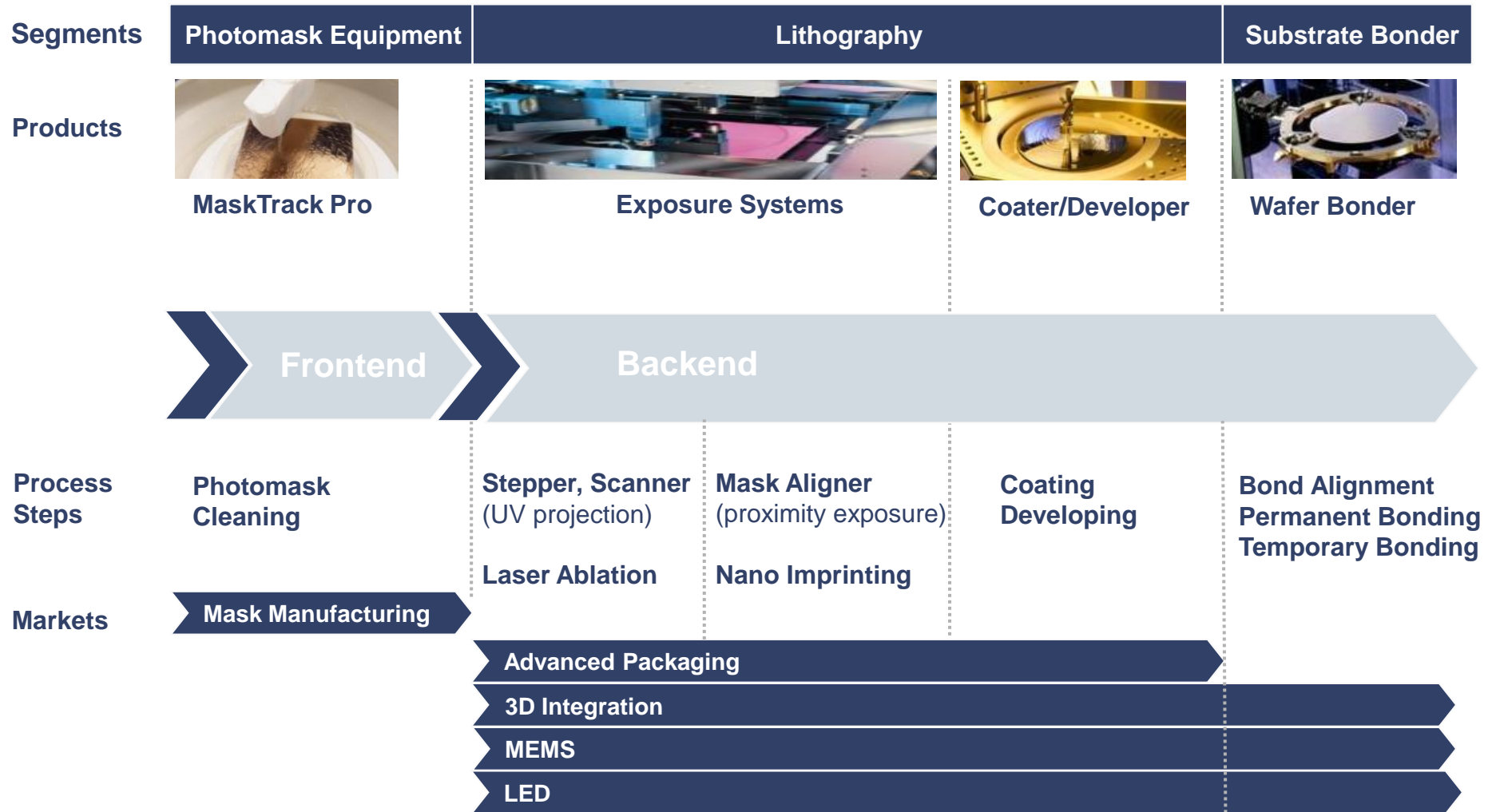


Semiconductors			Sensors	Lighting
Mask Manufacturing Photomask Cleaning	Advanced Packaging Micro-Bumping	3D Integration/Stacking	MEMS Computing, Automotive, Medical Applications ...	LED General Lighting, HB and UHB LED
 	 	 	 	 

SEGMENTS AND PRODUCTS

Segments	Photomask Equipment	Lithography		Substrate Bonder
Products	 MaskTrack Pro	 Exposure Systems	 Coater/Developer	 Wafer Bonder
				
Process Steps	Photomask Cleaning	Stepper, Scanner (UV projection) Laser Ablation	Mask Aligner (proximity exposure) Nano Imprinting	Coating Developing Bond Alignment Permanent Bonding Temporary Bonding
Key figures 2012	Sales: 22.9 € million EBIT: 1.1 € million	Sales: 113.2 € million EBIT: 23.7 € million		Sales: 23.1 € million EBIT: -12.0 € million

SEGMENTS AND MARKETS



OUR TECHNOLOGY ENABLES SUSTAINABILITY

Equipment

- SUSS MicroTec equipment is designed to efficiently use electricity and chemicals
- ReMan, the remanufacturing operation of SUSS MicroTec takes back used equipment and refurbishes it



Applications

- 3D IC and chip scaling helps reducing energy and material consumption
- LEDs for efficient lighting solutions
- MEMS applications improve performance of mobile devices and conserve energy
- Shift to renewable energies requires more power devices and high-performance ICs (e.g. for solar and wind power systems)
- Laser Ablation in lieu of photolithography (seed layer removal)

Initiatives

- Partner company of VDMA BlueCompetence initiative, a network of equipment providers in Germany, who are following a sustainable business approach
- Innovative lighting solution in Sternenfels
- Improved climatization system of cleanrooms
- Paperless invoice system

BLUECOMPETENCE

Alliance Member

Partner der Nachhaltigkeitsinitiative
des Maschinen- und Anlagenbaus

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MICROCHIPS, MEMS UND LED: BUILDING BLOCKS FOR TECHNOLOGICAL PRODUCT ADVANCEMENT

Digital Lifestyle

- The „Digital Lifestyle“ is characterized by permanent internet connectivity and convergence of media
- Mobile devices like smartphones and tablet PCs provide this capability at affordable cost
- New device generations offer higher functionality



E-Mobility

- Alternative transportation / mobility solutions are getting more traction with attractive price / performance ratios
- Evs, Hybrid-Cars, Segways, E-Bikes, but also trains drive the need for power devices but also high performance ICs



Energy Efficiency

- Increase environmental awareness and rising energy prices and fuel the demand for energy efficient solutions in electricity usage i.e. lighting
- Energy efficiency in industrial production
- Smart energy management in household applications saves energy



With its strong position in the fast growing target markets 3D Integration / Advanced Packaging, LED and MEMS, SUSS MicroTec can benefit from the market developments:

Advanced Packaging

Wafer level packaging and flip chip is expected to remain more robust than the overall market, primarily driven by mobile devices like smart phones and tablets

3D Integration (TSV)

Transition to production volume in the years to come

Compound Semiconductors

LED, MEMS, RF, Optoelectronics, III-V Power are expected to remain robust based on smartphone and tablet growth and will drive further demand for advanced packaging solutions

Segment growth 2011 - 2016E CAGR ~ 15% (Gartner and industry estimates)

SCALING TECHNOLOGIES FROM 2D TO 3D

2D Packaging

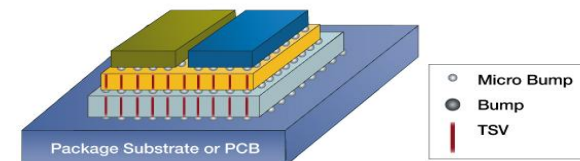
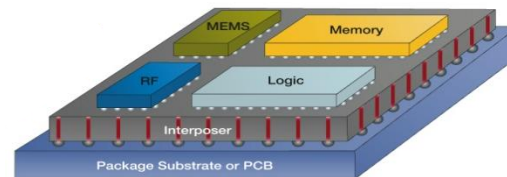
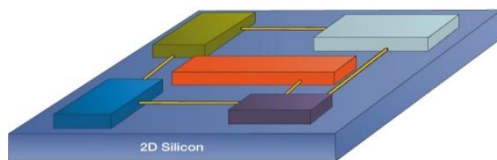
- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore's Law
- New technologies like EUV and multiple patterning allow further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size

2.5D Packaging

- Combining of several (and heterogeneous) semiconductor components on an interposer addresses limitations of traditional shrinking
- Increased packaging density
- Reduced footprint
- Complementary technology to Moore's Law

3D Integration (TSV)

- The extension beyond the conventional shrink roadmap is called "More than Moore"
- Packaging becomes key enabler for scaling and some manufacturing value is shifting from silicon to the package
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption



SUSS MicroTec's equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 3D stacking ("*More than Moore*")

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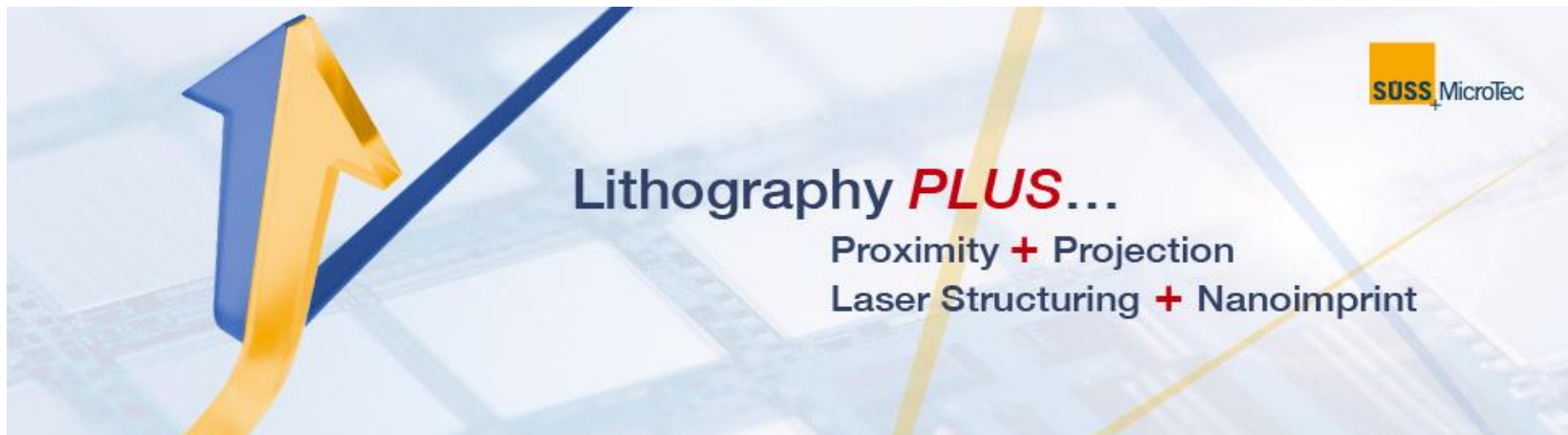
- + SUSS MicroTec Photonic Systems develops and builds UV projection lithography systems and laser micro-structuring tools
- + The Company targets the same high growth market segments as SUSS MicroTec: Advanced Packaging, 3D Integration, MEMS and LED

+ Key Data:

- Founded 1966, based in Corona, California
- Installed base larger than 1,100 systems
- Revenues FY11/12: app. 10 million €
- 63 employees
- Total purchase price 9.34 million \$
(plus additional variable earn-out component)



- + Increasing chip performance requires adoption of innovative lithography technologies in the semiconductor backend
- + **Not one technology fits all needs**
- + Add new and highly complementary product line with the core technologies UV projection lithography and laser micro-structuring
- + SUSS MicroTec's global sales and support structure plus SUSS MicroTec Photonic Systems' (former Tamarack Scientific) technology offering enables the expansion of SUSS MicroTec's lithography footprint
- + SUSS MicroTec as a financially strong and globally positioned company can unlock the potential of Tamarack and enable high future growth



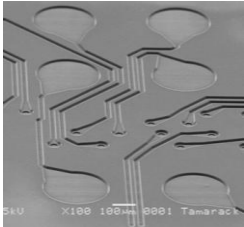
Our Lithography Solutions

EVOLUTION REVOLUTION

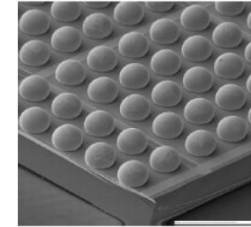
- + Established:**
 - Proximity Exposure Systems
 - NanoImprint
- + Evolution:**
 - Innovative UV Lithography Alternatives:
 - Full field projection scanner
 - Projection stepper
- + Revolution:**
 - Laser Patterning



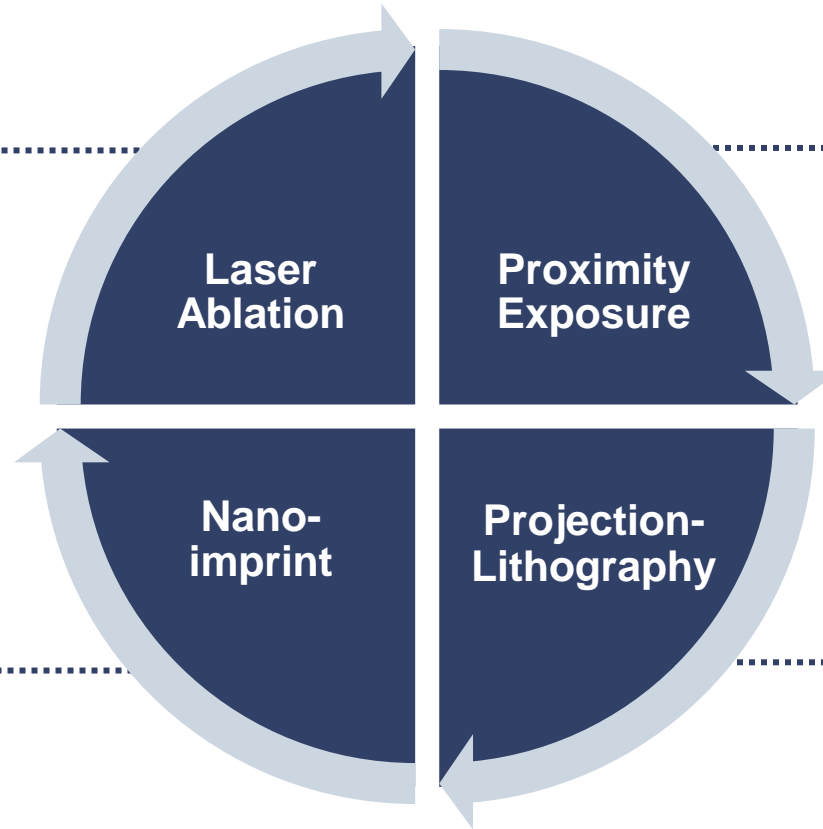
**SUSS MicroTec to become the leading provider
for mid- and backend lithography systems**



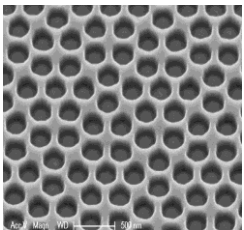
WLCSP:
Fanout WLP



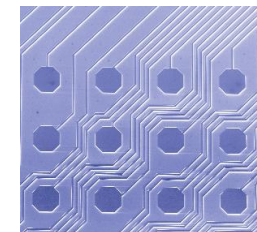
Flip Chip:
Solder Bumping



LED:
Photonic Crystals



WLCSP:
Fine pitch RDL



SUSS MicroOptics is leading supplier for advanced micro-optics
Field of use is among others semiconductor lithography (i.e. Carl Zeiss, SUSS MicroTec), telecommunications and R&D

Our technology and innovation leadership position is a solid base for continuous future growth, over the last 10 years a CAGR of 20% could be achieved

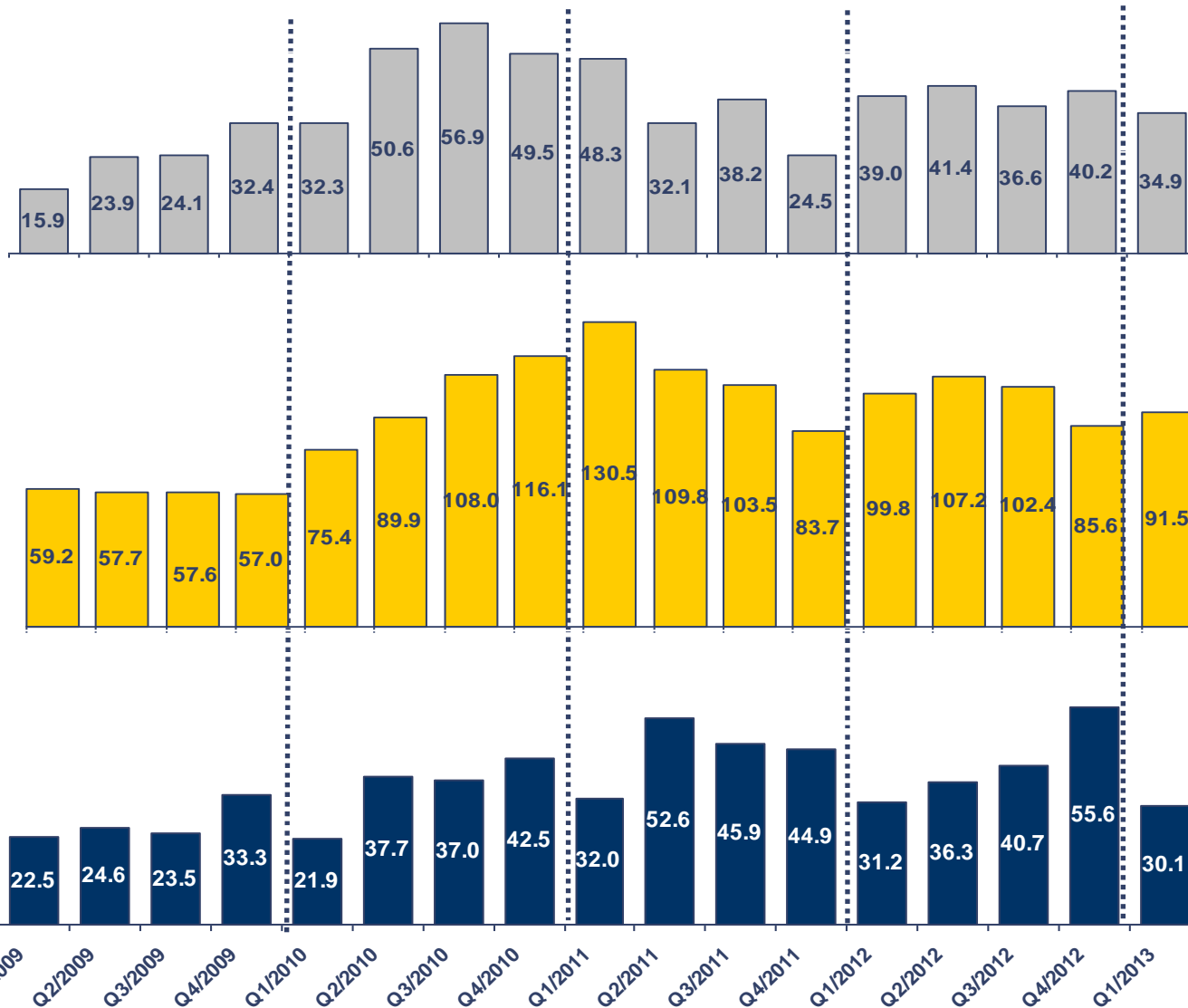
In November 2012 SUSS MicroOptics moved into a new production facility:

- Class 100/1000 cleanroom (415sqm)
- Total investment of more than € 2 million
- Production start mid December 2013
- New fab allows to move from one shift (8h/5d) to 24/7 operation



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LONG TERM BUSINESS DEVELOPMENT



Order Entry

in € million

2012: € 157.2 million

Order Backlog

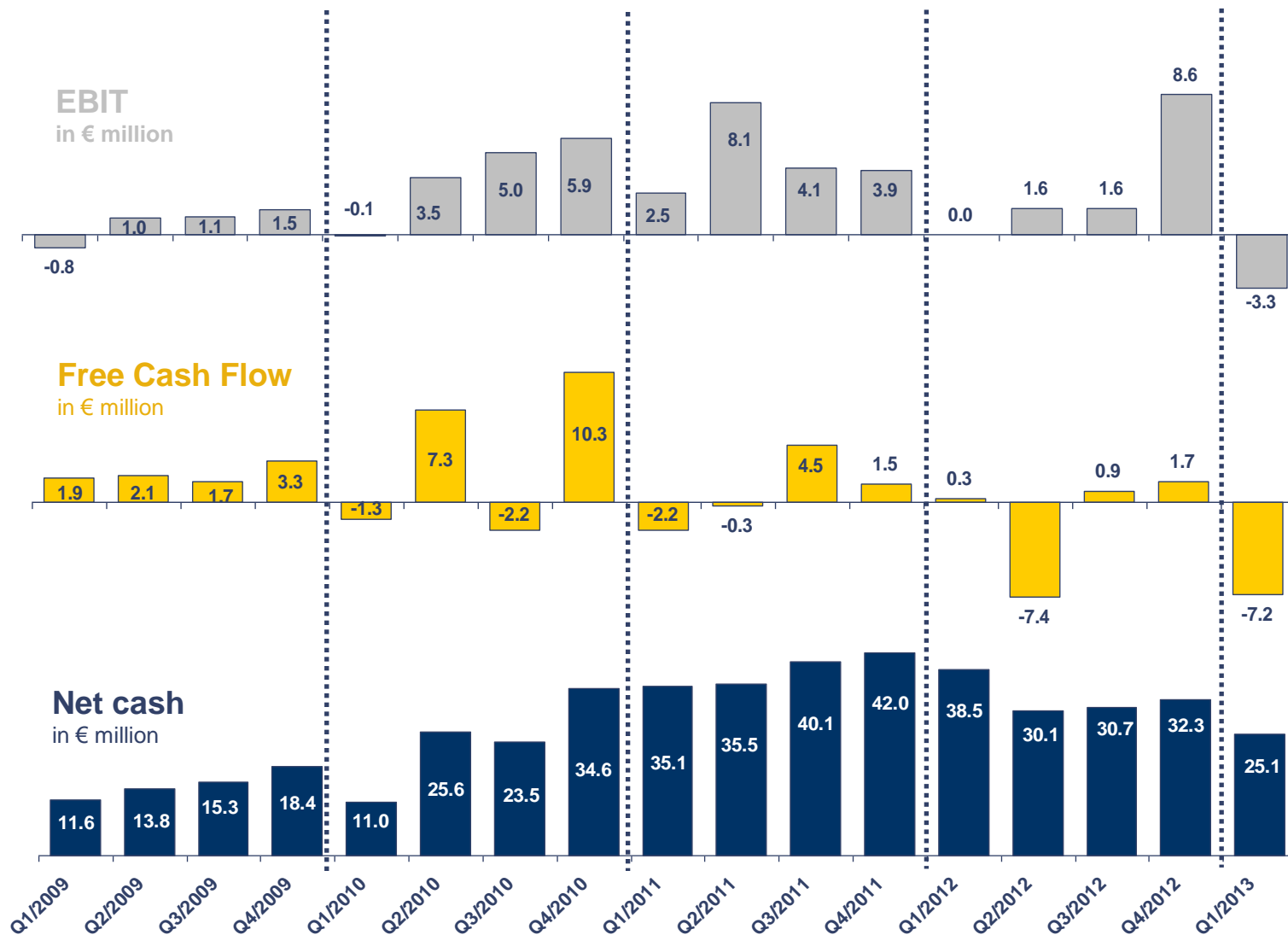
in € million

Sales

in € million

2012: € 163.8 million

EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



KEY FINANCIALS

in € million	Q1 2013	Q1 2012	in %	2012	2011
Order Intake	34.9	39.0	-10.5%	157.2	143.1
Order Backlog 3/31	91.5	99.8	-8.3%	86.5	83.7
Revenue	30.1	31.2	-3.5%	163.8	175.4
EBIT	-3.3	0	--	11.7	18.6
<i>EBIT in % of Sales</i>	<i>-11.0%</i>	<i>0%</i>	<i>--</i>	<i>7.1%</i>	<i>10.6%</i>
Earnings after tax (continuing operations)	-2.5	-0.2	<-100%	7.6	13.8
Earnings after tax	-2.5	1.3	--	9.1	13.8
EPS in €	-0.13	0.07	--	0.40	0.72
Free Cash Flow*	-7.2	0.3	--	-4.5	3.5
Net Cash**	25.1	38.5	-34.8%	32.3	43.0
Employees 3/31	693	687	+0.9%	704	624

* before consideration of purchased interest-bearing securities , the acquisition of Tamarack and the gain out of the sale from the Test Business

** incl. stock of interest-bearing securities

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Guidance

- + FY 2013:
 - Sales of approximately 150 € million
 - EBIT: negative mid-to-high single digit million € range
- + Q2 2013:
 - Order Intake 30 – 40 € million

Investment Case

- + Strong fundamental growth in target markets
- + Strong competitive positioning:
first or second in the target markets
- + Leading equipment company in the semiconductor backend, enabling “Moore’s Law” as well as “More than Moore”
- + Leading Mid- and Backend Lithography company
- + Significant mid term revenue opportunity



Thank you!

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www.SUSS.com

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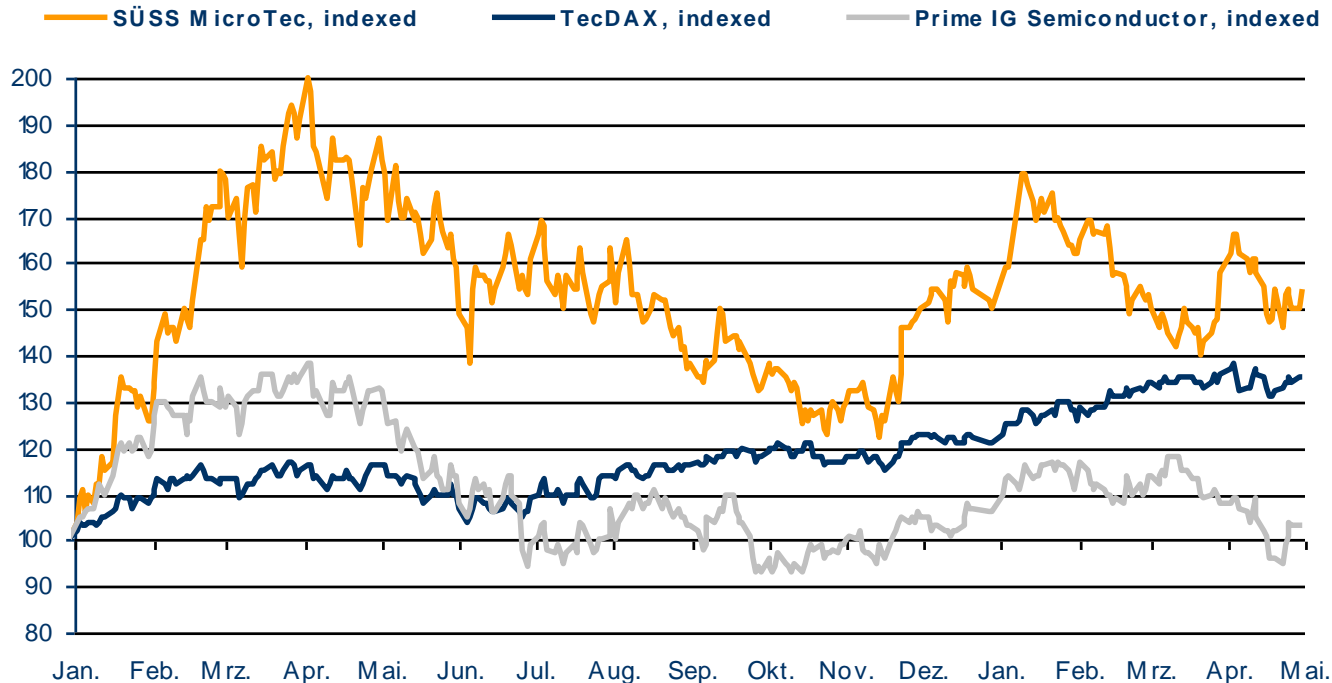
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Financial Calendar 2013

Quarterly Report 2013	8. May
Commerzbank German Midcap Conference, Boston/New York	22./23. May
DZ Bank Sustainability Conference, Zurich	4. Jun.
Shareholders' Meeting, Haus der Bayerischen Wirtschaft, Munich	19. Jun.
Interim Report 2013	8. Aug.
Commerzbank TMT Conference, Frankfurt	28. Aug
Bankhaus Lampe German Technology Seminar, Zurich	13. Sep.
UBS Best of Germany Conference, New York	16. - 18. Sep
UniCredit/Kepler Investment Conference, Munich	24. - 26. Sep
Baader Investment Conference, Munich	24. - 26. Sep
Nine-month Report 2013	7. Nov.
German Equity Forum, Frankfurt/Main	11. - 13. Nov

SUSS MICROTEC SHARE PRICE DEVELOPMENT

(Price of the SUSS MicroTec Share at December 30, 2011, € 5.63)



Major Shareholders:

DWS Germany 8.68%

Credit Suisse Switzerland 3.35%

BlackRock 3,23%

Henderson Global Invest. 3.14%

DWS Luxembourg 3.04%

Average daily trading volume 2012/13: ~ 114,000